

STACKED VIA STRUCTURE THAT INCLUDES A SKIP VIA

Abstract of the Disclosure

In various embodiments, the present invention relates to a substrate that
5 may include vias for communicating signals throughout the substrate. The
substrate includes a plurality of dielectric layers and a stack of vias that may be
formed on a core. One of the vias may be a first skip via that extends through at
least two of the dielectric layers, while another via may extend through at least
one other of the dielectric layers. The second via and the first skip via are
10 stacked on top of one another. In another sample embodiment of the substrate,
the second via may be a second skip via that extends through at least two
dielectric layers.

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